Bond-Ply® 100

Thermally Conductive, Fiberglass Reinforced Pressure Sensitive Adhesive Tape

Features and Benefits

- Thermal impedance: 0.86°C-in²/W (@100 psi)
- High bond strength to a variety of surfaces
- Double-sided, pressure sensitive adhesive tape
- High performance, thermally conductive acrylic adhesive
- Can be used instead of heat-cure adhesive, screw mounting or clip mounting



Typical Applications Include:

- Mount heat sink onto BGA graphic processor or drive processor
- Mount heat spreader onto power converter PCB or onto motor control PCB

Configurations Available:

• Sheet form, roll form, and die-cut parts

Shelf Life: The double-sided, pressure sensitive adhesive used in Bond-Ply products requires the use of dual liners to protect the surfaces from contaminants. Bergquist recommends a 6-month shelf life at a maximum continuous storage temperature of 35°C, or 3-month shelf life at a maximum continuous storage temperature of 45°C, for maintenance of controlled adhesion to the liner. The shelf life of the Bond-Ply material, without consideration of liner adhesion (which is often not critical for manual assembly processing), is recommended at 12 months from date of manufacture at a maximum continuous storage temperature of 60°C.

TYPICAL PROPERTIES OF BOND-PLY 100						
PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	White		White		Visual	
Reinforcement Carrier	Fiberglass		Fiberglass		_	
Thickness (inch) / (mm)	0.005, 0.008, 0.011		0.127, 0.203, 0.279		ASTM D374	
Temp. Resistance, 30 sec. (°F) / (°C)	392		200		_	
Elongation (%45° to Warp & Fill)	70		70		ASTM D412	
Tensile Strength (psi) / (MPa)	900		6		ASTM D412	
CTE (ppm)	325		325		ASTM D3386	
Glass Transition (°F) / (°C)	-22		-30		ASTM 1356	
Continuous Use Temp (°F) / (°C)	-22 to 248		-30 to 120		_	
ADHESION						
Lap Shear @ RT (psi) / (MPa)	100		0.7		ASTM D1002	
Lap Shear after 5 hr @ 100°C	200		1.4		ASTM D1002	
Lap Shear after 2 min @ 200°C	200		1.4		ASTM D1002	
Static Dead Weight Shear (°F) / (°C)	302		150		PSTC#7	
ELECTRICAL			VALUE		TEST METHOD	
Dielectric Breakdown Voltage - 0.005" (Vac)			3000		ASTM D149	
Dielectric Breakdown Voltage - 0.008" (Vac)			6000		ASTM D149	
Dielectric Breakdown Voltage - 0.011" (Vac)			8500		ASTM D149	
Flame Rating			V-O		U.L.94	
THERMAL						
Thermal Conductivity (W/m-K)			0.8		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Pres	sure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W) 0.005"		4.39	4.02	3.48	3.15	3.05
TO-220 Thermal Performance (°C/W) 0.008"		5.11	4.69	4.53	4.45	4.38
TO-220 Thermal Performance (°C/W) 0.011"		6.26	5.92	5.73	5.63	5.53
Thermal Impedance (°C-in²/W) 0.005" (1)		0.78	0.61	0.58	0.55	0.54
Thermal Impedance (°C-in²/W) 0.008" (1)		1.28	0.94	0.90	0.86	0.84
Thermal Impedance (°C-in²/W) 0.011" (1)		2.47	1.22	1.19	1.14	1.11
1) The ASTM D5470 (Bergquist modified) test fixture was used. The recorded value includes interfacial thermal resistance. These						

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Building a Part Number

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level. 11/250 = 11" x 250' rolls, or 00 = custom configuration 00 = No adhesive

BPI00 = Bond-Ply I00 Material

Standard thicknesses available: 0.005", 0.008", 0.011"

Standard Options

Note: To build a part number, visit our website at www.bergquistcompany.com.

Bond-Ply®: U.S. Patent 5,090,484 and others.

BERTOUIST

www.bergquistcompany.com